



Attorney Docket No. 401134/ASAHINA

PATENT

9/18
7. Septoe
10-23-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

TAKATA et al.

Application No. 09/808,151

Filed: March 15, 2001

For: SEMICONDUCTOR PACKAGE

Art Unit: 2815

Examiner: A. Wilson

RESPONSE TO OFFICE ACTION

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated July 17, 2002, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE DRAWINGS:

The Examiner is requested to approve the changes to Figures 16-18 as indicated in the attached Request for Approval of Drawing Amendments.

IN THE CLAIMS:

Cancel claims 1 and 8 and replace the indicated claims with:

1. (Twice Amended) A semiconductor package comprising:
a semiconductor chip,

a die pad,

a die bonding material fixing the semiconductor chip to the die pad,

lead-on-chip (LOC) inner leads having tips spaced from and extending across the

semiconductor chip,

standard inner leads,

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cont.

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